# 2018

COMPUTATIONAL DESIGN AND SIMULATION OF MATERIALS



TMS 2018
147th Annual Meeting & Exhibition
March 11 – 15, 2018
Phoenix, Arizona

Don't miss your opportunity to present your work at the 2nd International Conference on Computational Design and Simulation of Materials (CDSM 2018). Organized jointly by TMS and the Chinese Society for Metals (CSM), CDSM 2018 offers a complete meeting-within-a-meeting experience, focused on computational simulation and modeling to accelerate materials discovery and design.

## CDSM2018: MESO/MACROSCALE SIMULATIONS

Submit Your Abstract at tms.org/CDSM2018

Microstructural attributes to processing and property modeling of materials play a central role in materials design and multi-scale modeling. Their quantification and insertion into models are highly desirable. This symposium seeks to advance progress in this area through discussion of topics at scales above atoms, with a particular interest in integration of scales.

Specific topic areas for abstract submissions include (but are not limited to):

- Dislocations and dislocation dynamics
- Phase transition modeling
- Microstructural evolution by phase-field simulations
- Manufacturing process simulations
- Materials under extreme conditions
- Multi-scale modeling and simulations: tools and properties

#### CDSM 2018 CO-CHAIRS:

**Zi-Kui Liu**, Pennsylvania State University **Alan Luo**, The Ohio State University

## **SUBMIT YOUR ABSTRACT ONLINE:**

tms.org/CDSM2018

Questions? Contact programming@tms.org

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